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(12) United States Design Patent

Kanda et al.

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(54) **SEMICONDUCTOR MODULE**

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(73) Assignee: **ROHM CO., LTD.**, Kyoto (JP)

(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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Apr. 13, 2018 (JP) 2018-008233

(51) **LOC (12) Cl.** **13-03**
(52) **U.S. Cl.**
USPC **D13/182**
(58) **Field of Classification Search**
USPC D13/182
(Continued)

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(74) *Attorney, Agent, or Firm* — Hamre, Schumann, Mueller & Larson, P.C.

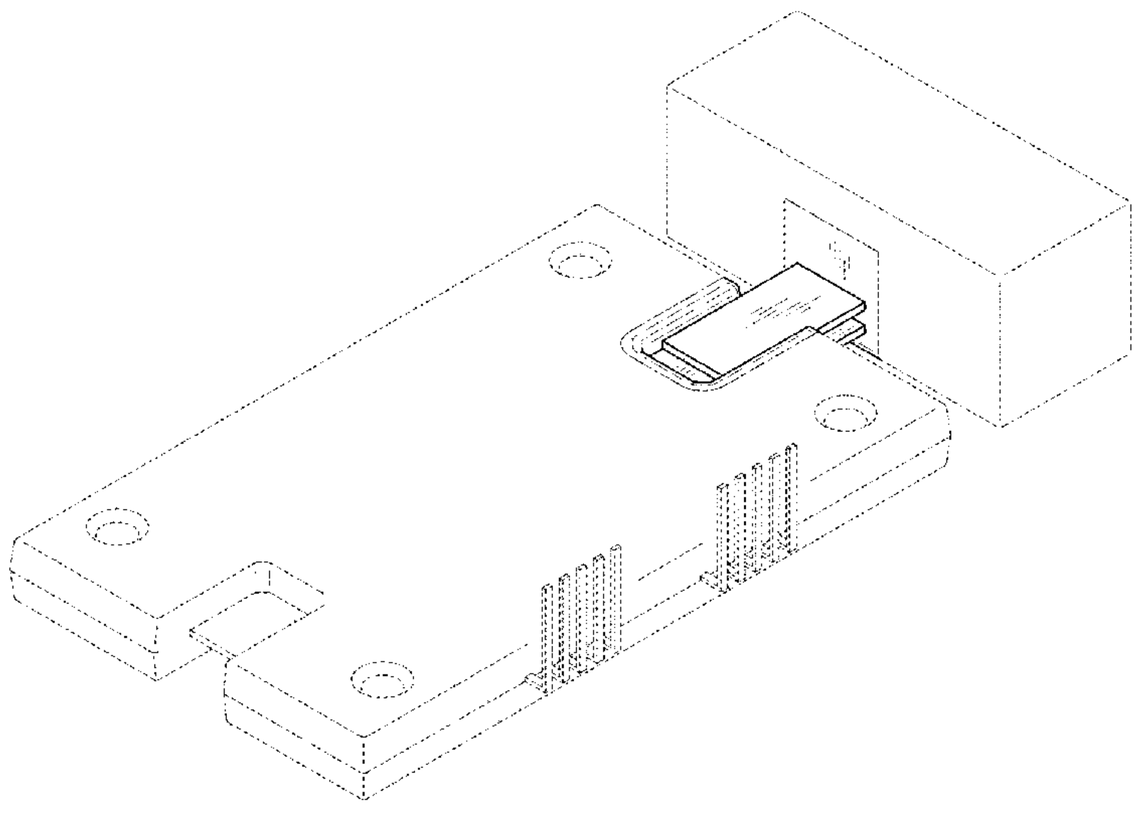
(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. **1** is a front, top and left side perspective view of a first embodiment of a semiconductor module showing our new design;
FIG. **2** is a rear, bottom, and right side perspective view thereof;
FIG. **3** is a front view thereof;
FIG. **4** is a rear view thereof;
FIG. **5** is a top plan view thereof;
FIG. **6** is a bottom plan view thereof;
FIG. **7** is a left side view thereof;
FIG. **8** is an enlarged cross-sectional view at the portion of **8-8** taken along line **8-8** in FIG. **5**;
FIG. **9** is an enlarged cross-sectional view taken along line **9-9** in FIG. **5**;
FIG. **10** is a front, top and left side perspective view of a second embodiment of a semiconductor module showing our new design;
FIG. **11** is a rear, bottom, and right side perspective view thereof;
FIG. **12** is a front view thereof;
FIG. **13** is a rear view thereof;
FIG. **14** is a top plan view thereof;
FIG. **15** is a bottom plan view thereof;
FIG. **16** is a left side view thereof;
FIG. **17** is an enlarged cross-sectional view at the portion of **17-17** taken along line **17-17** in FIG. **14**; and,
FIG. **18** is an enlarged cross-sectional view taken along line **18-18** in FIG. **14**.
The broken lines illustrate portions of the semiconductor module and form no part of the claimed design. The dash-dotted lines denote the boundary of the claim and form no part of the claimed design.

1 Claim, 18 Drawing Sheets



(58) **Field of Classification Search**

CPC H01L 21/02428; H01L 21/0243; H01L 21/02494; H01L 21/02496; H01L 21/02499; H01L 21/02502; H01L 21/02505; H01L 21/02507; H01L 21/0251; H01L 21/02513; H01L 21/02587; H01L 21/0259; H01L 21/02592; H01L 21/02595; H01L 21/02598; H01L 21/02603; H01L 21/02606; H01L 23/04; H01L 23/041; H01L 23/043; H01L 23/045; H01L 23/047; H01L 23/049; H01L 23/051; H01L 23/053; H01L 23/055; H01L 23/057; H01L 23/06; H01L 23/08; H01L 23/10; H01L 23/452; H01L 23/4922; H01L 29/02; H01L 29/04; H01L 29/045; H01L 29/06; H01L 29/0603; H01L 29/0657; H01L 29/0665; H01L 29/0684

See application file for complete search history.

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D717,256	S	*	11/2014	Sohn	D13/182
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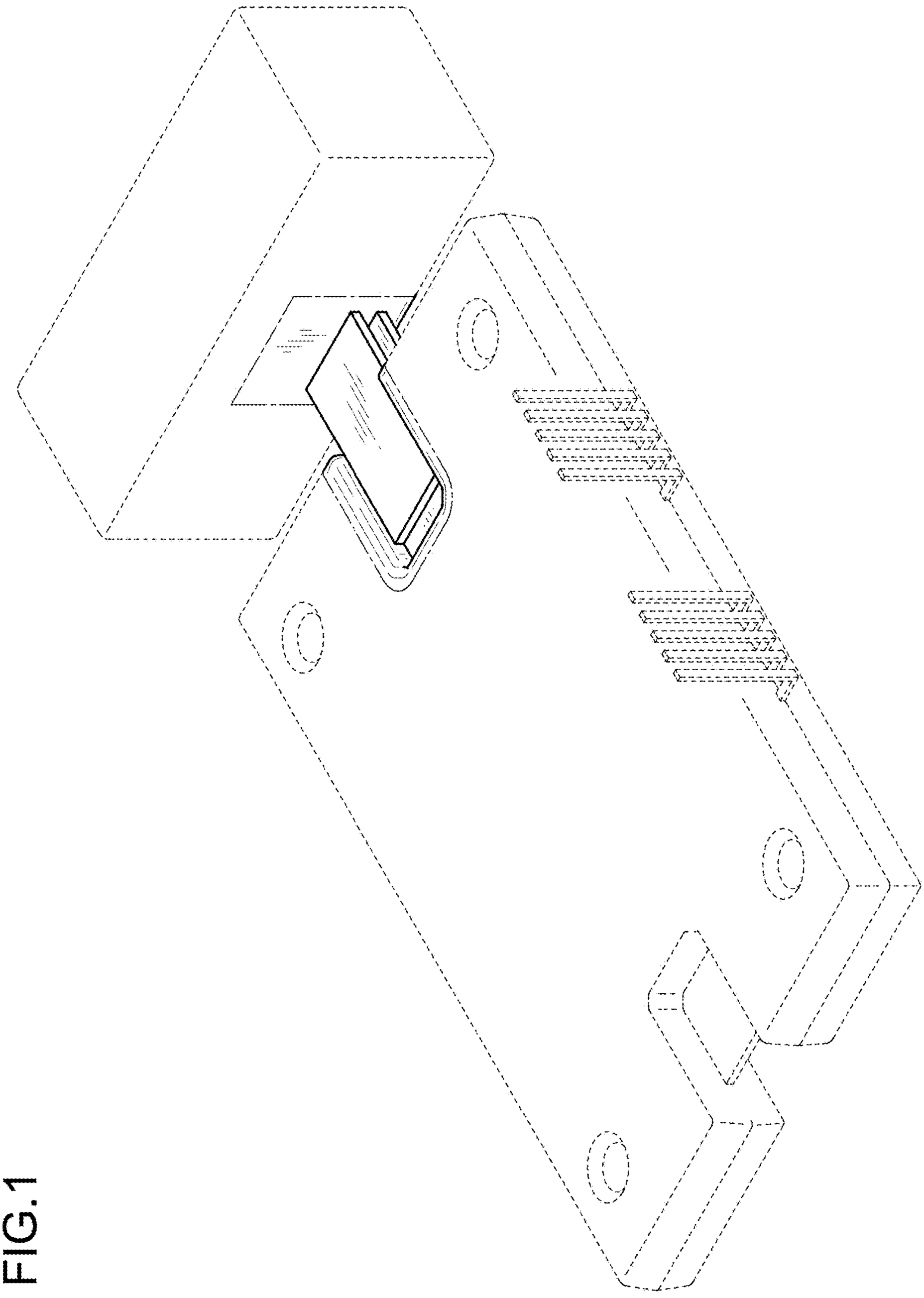

FIG.1

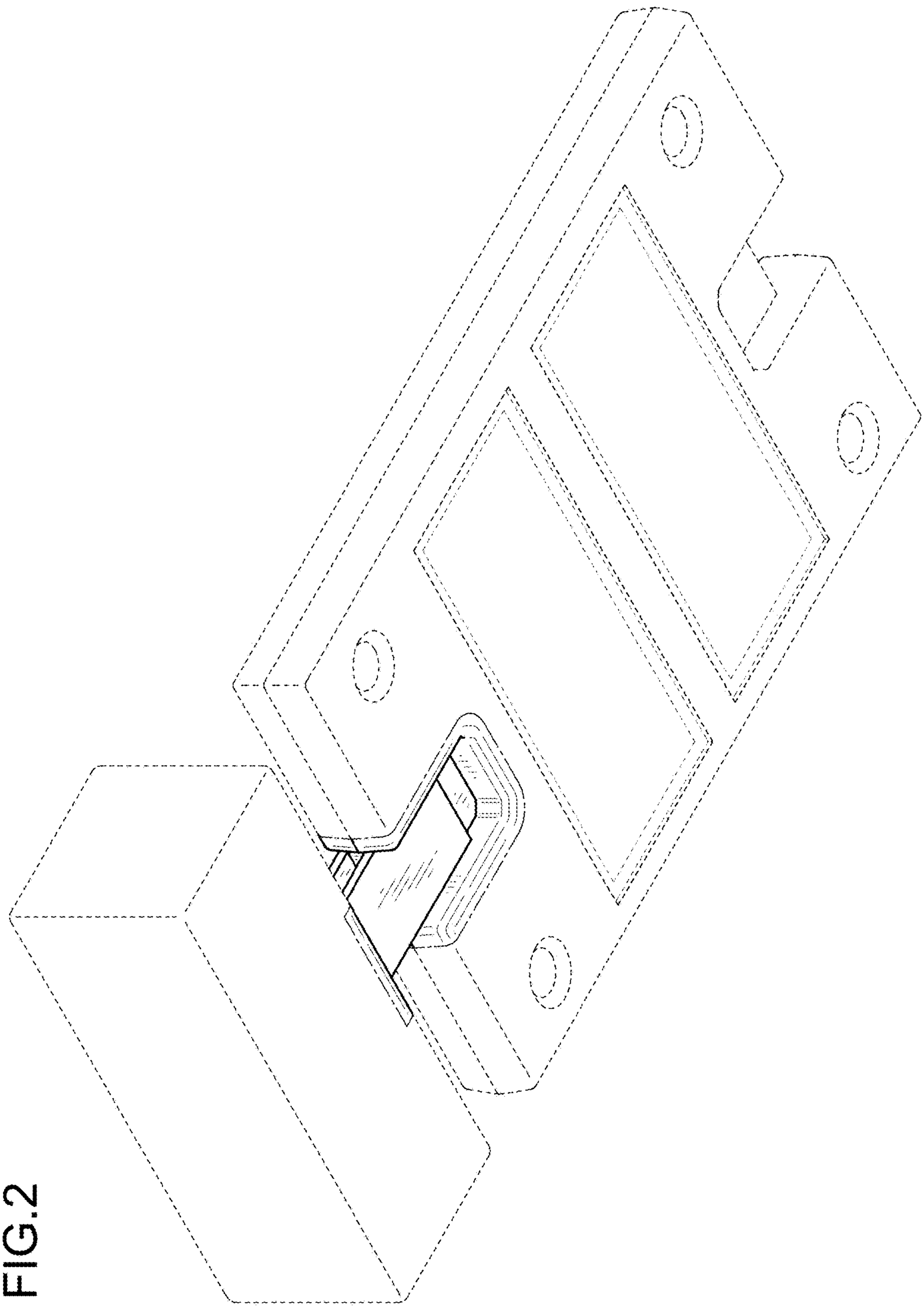

FIG.2

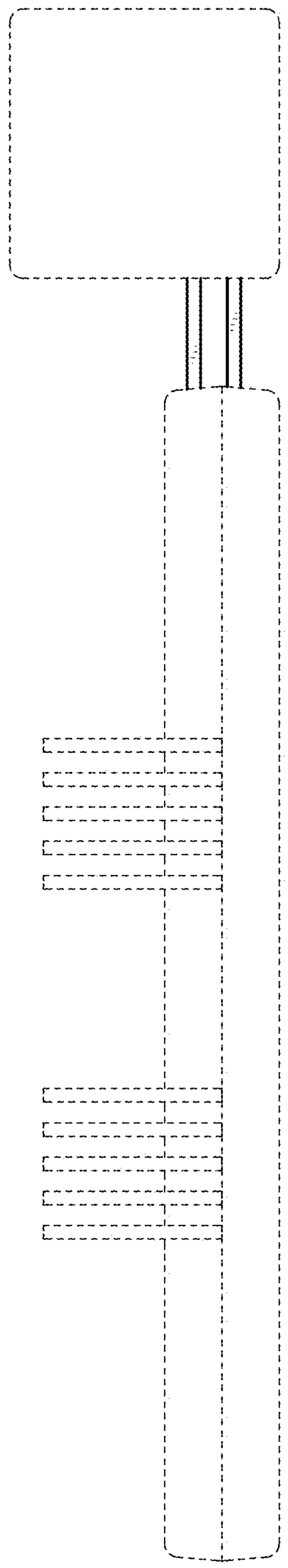

FIG.3

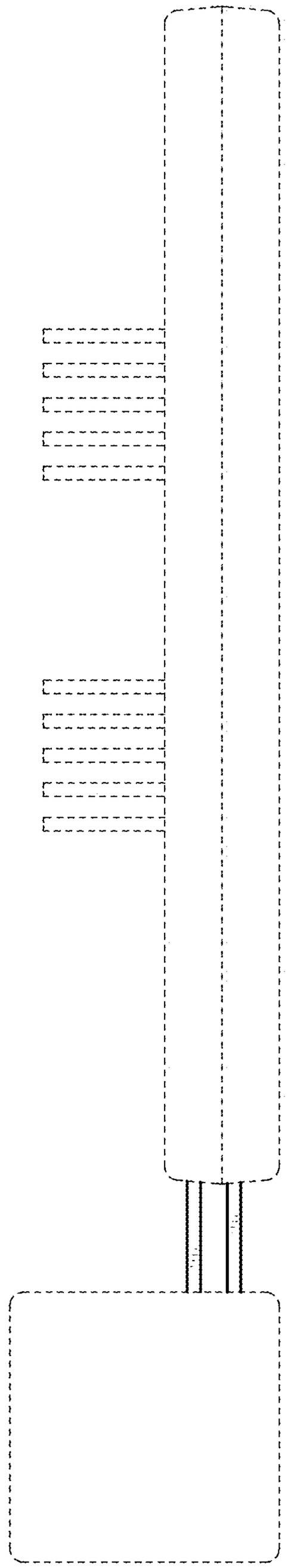

FIG.4

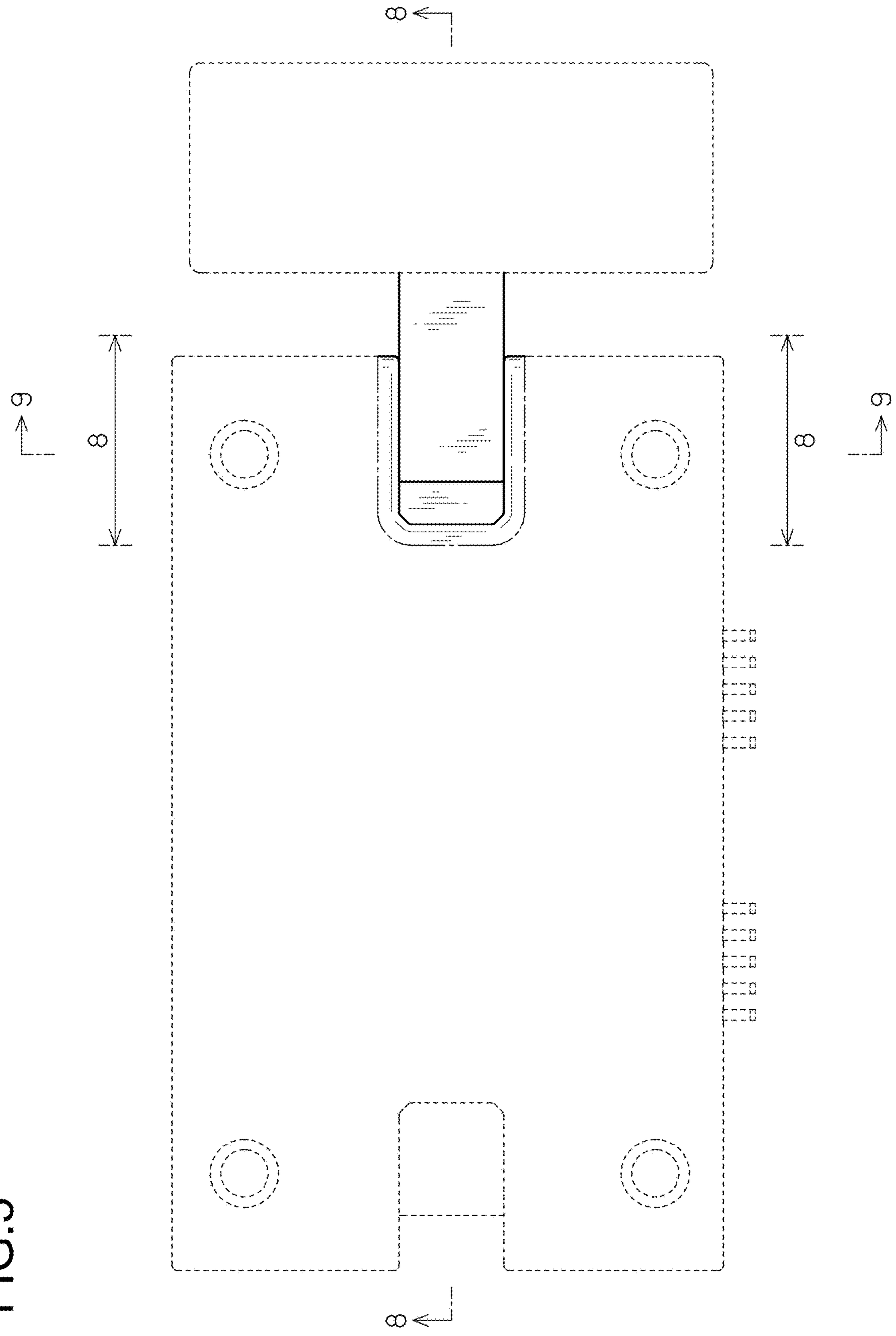

FIG.5

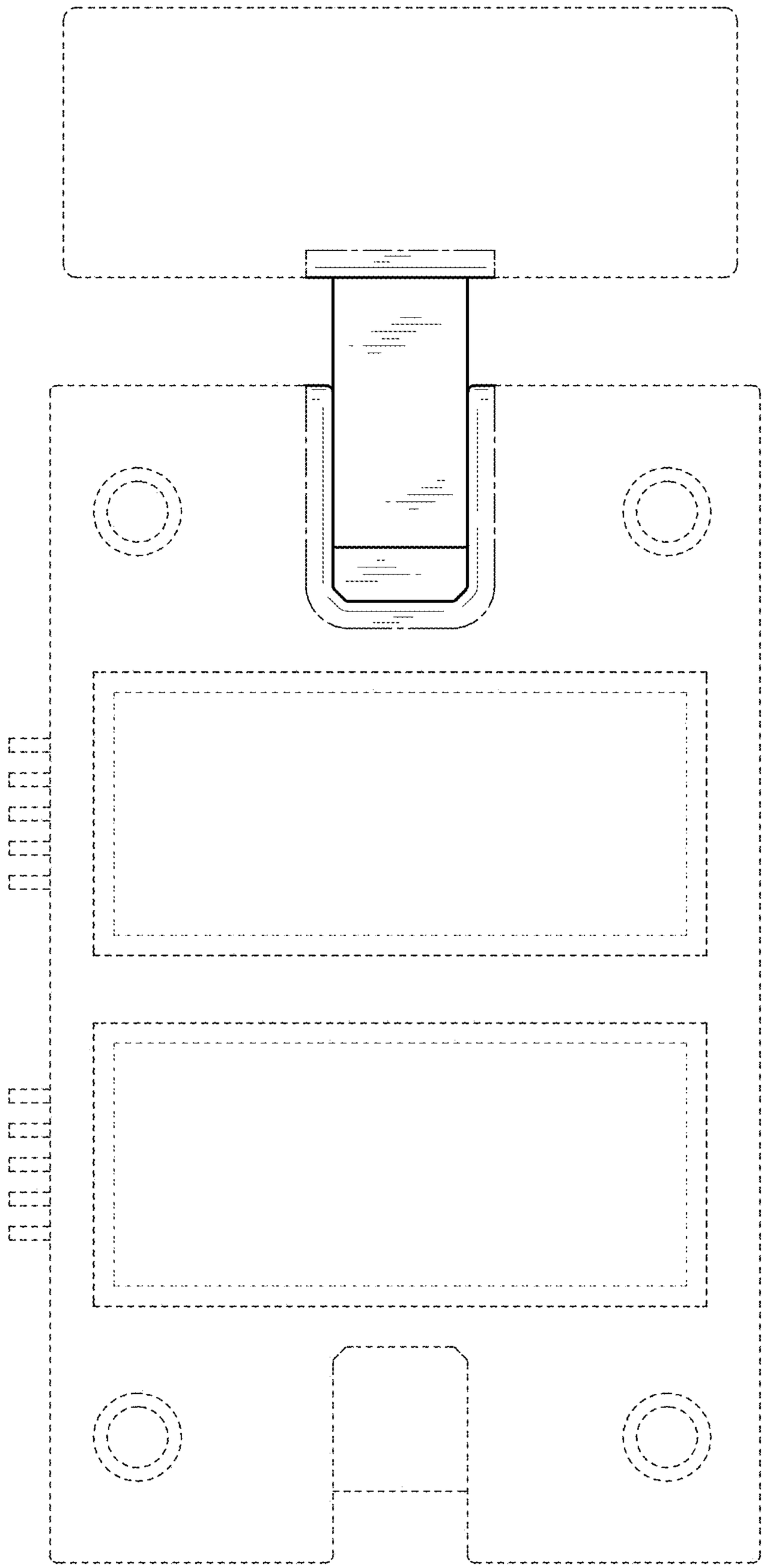

FIG.6

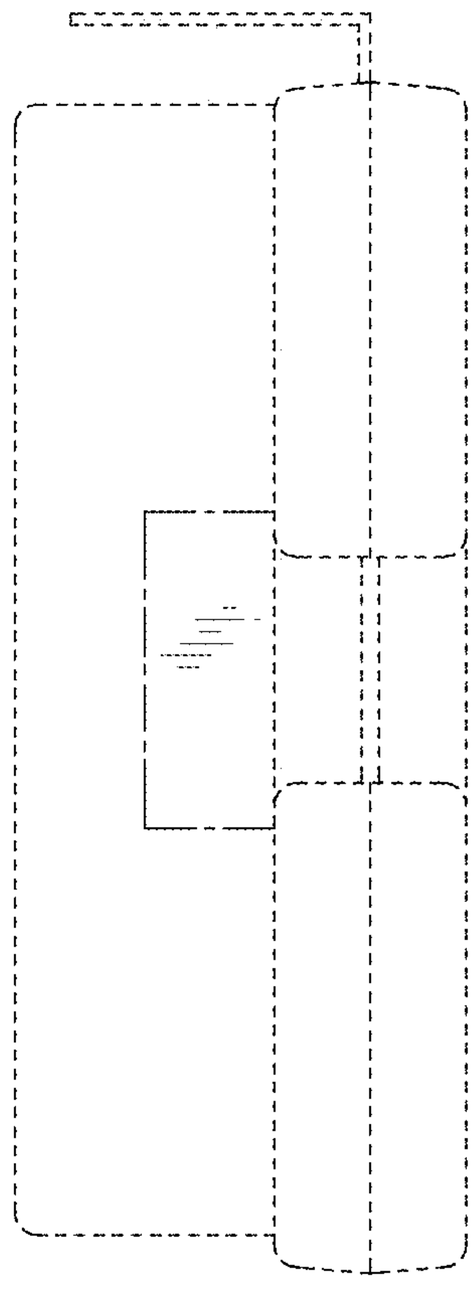

FIG.7

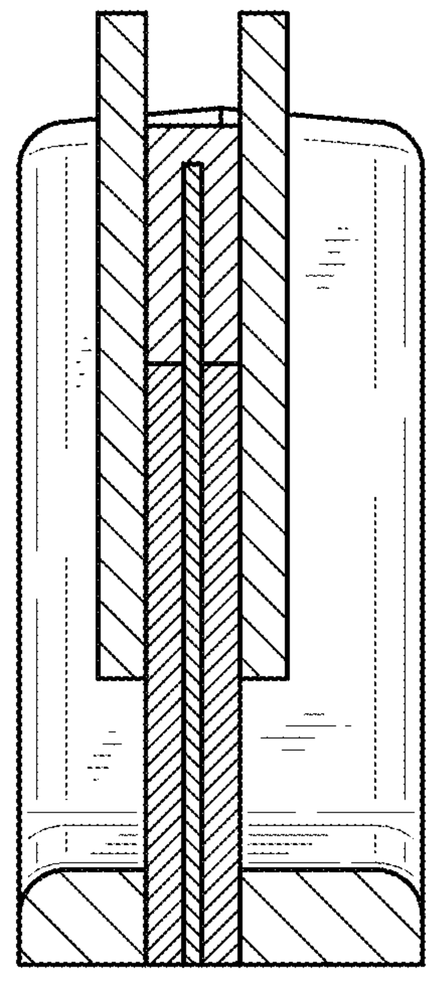

FIG.8

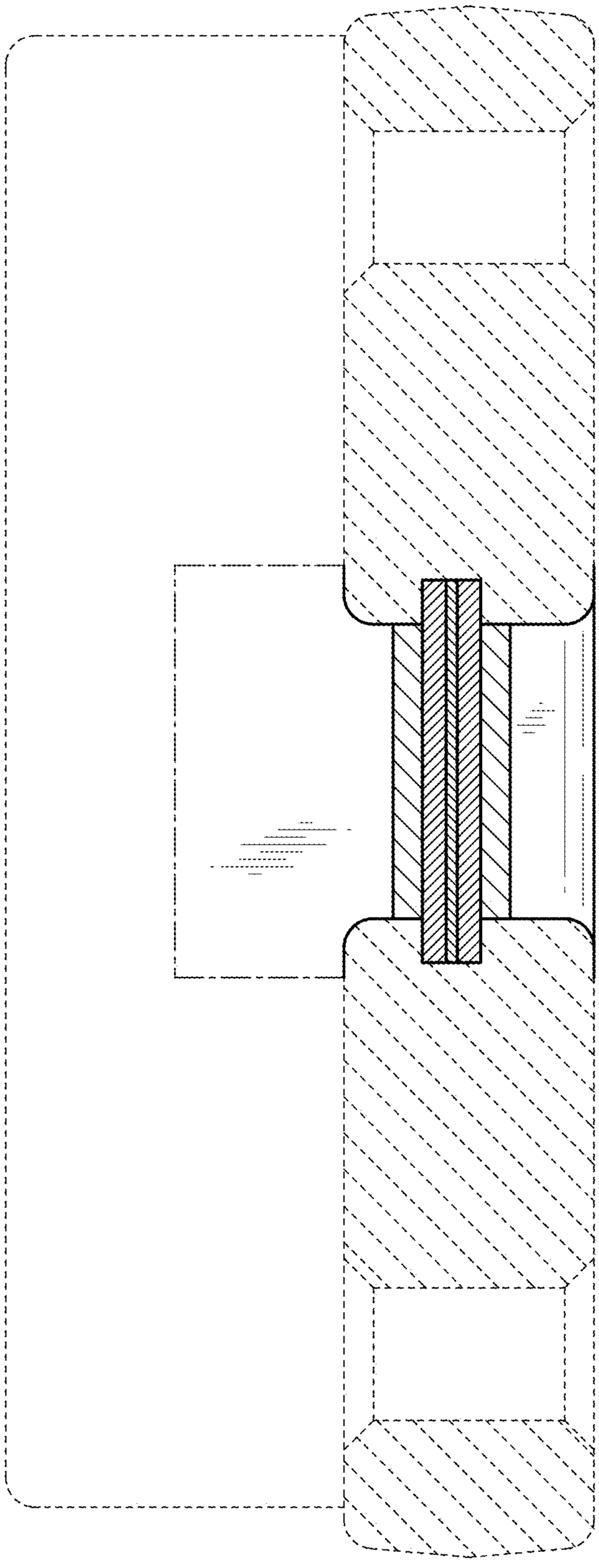

FIG.9

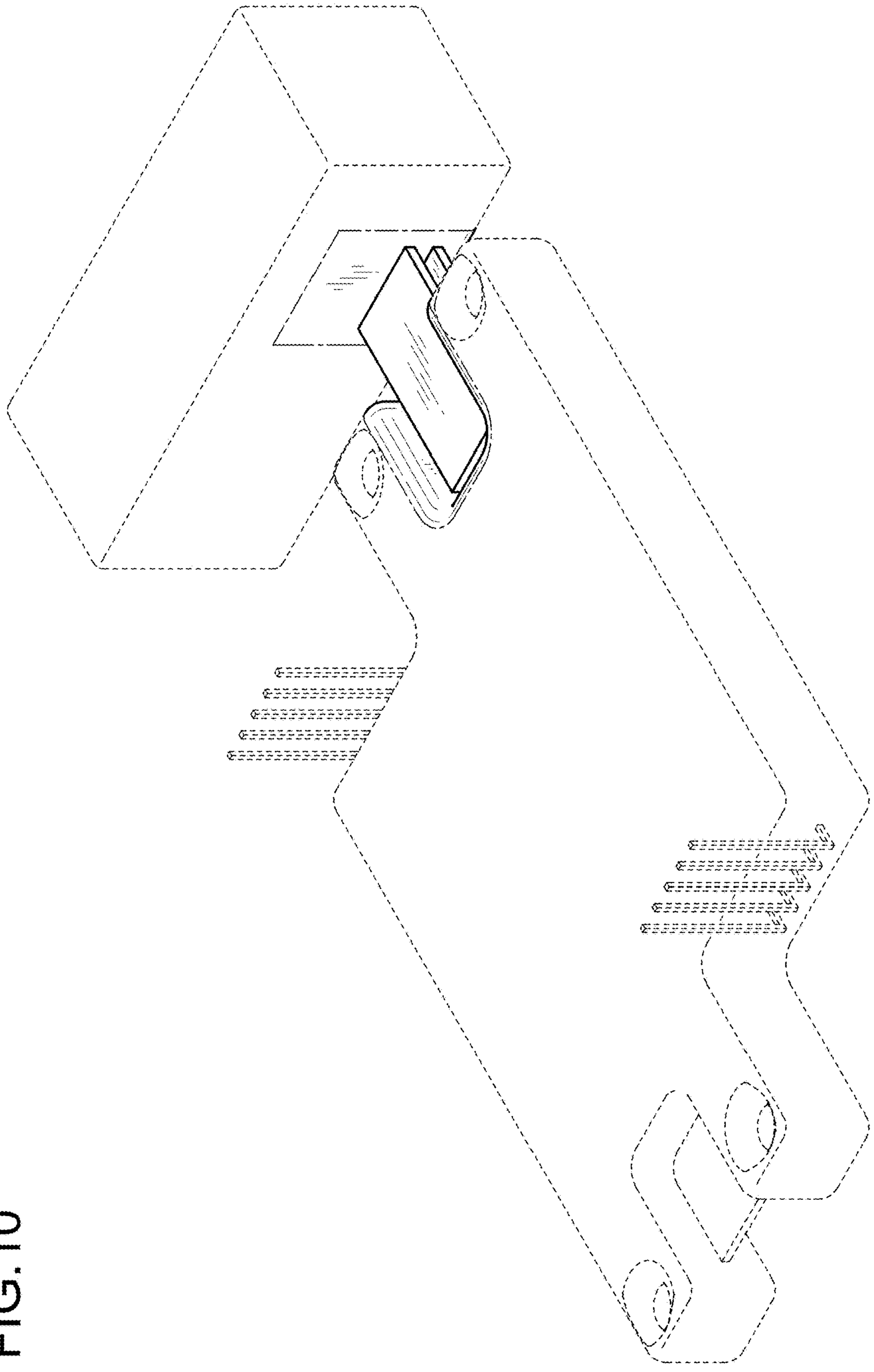

FIG.10

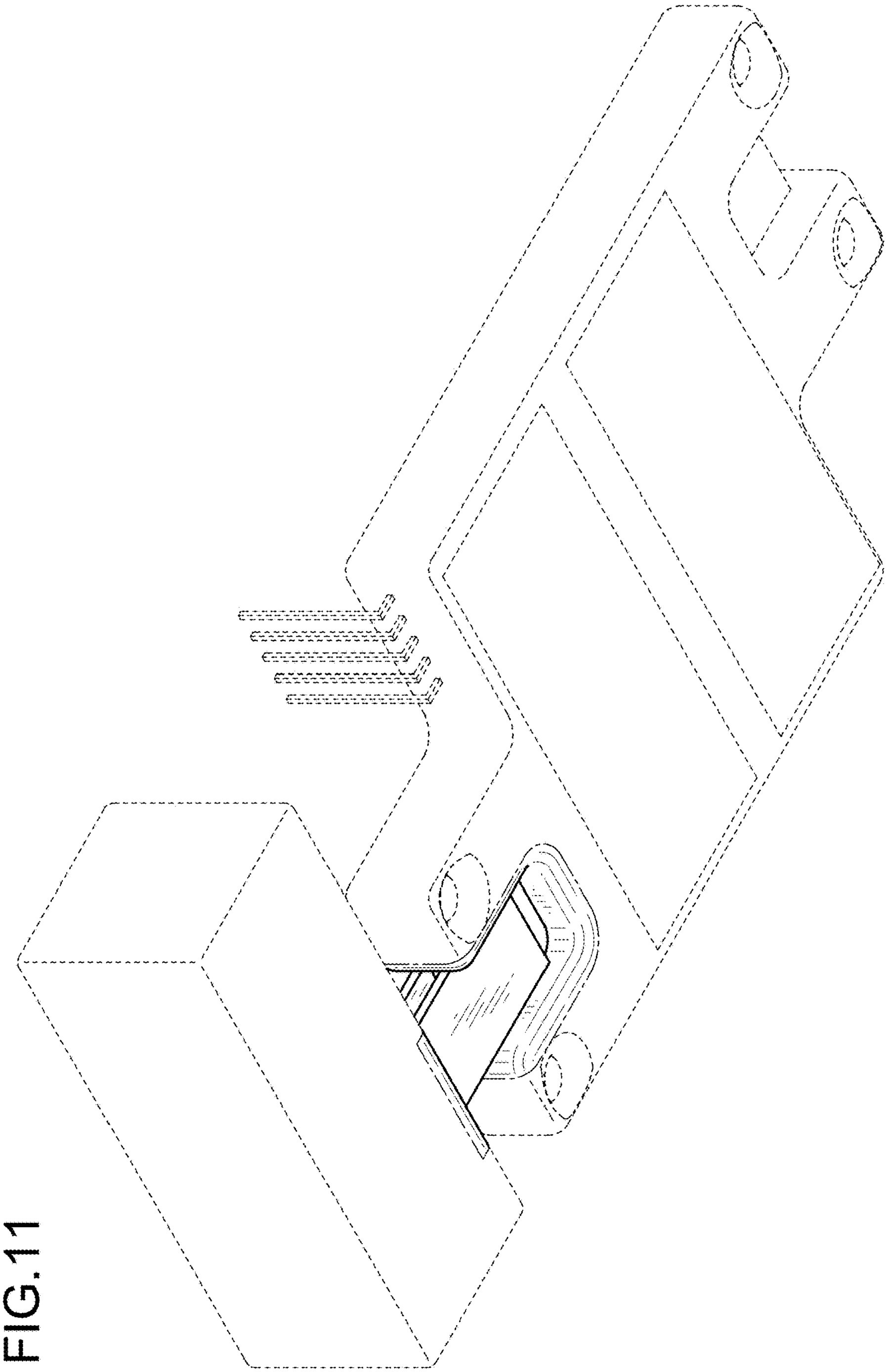

FIG.11

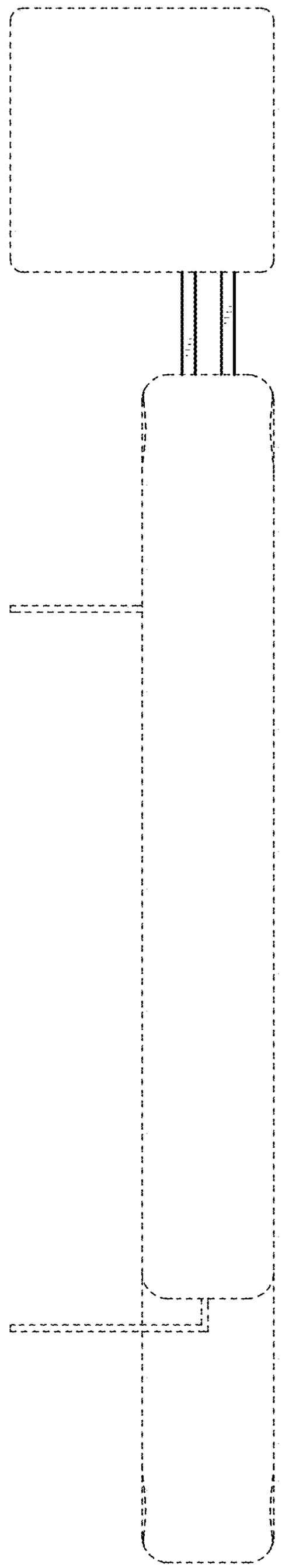

FIG.12

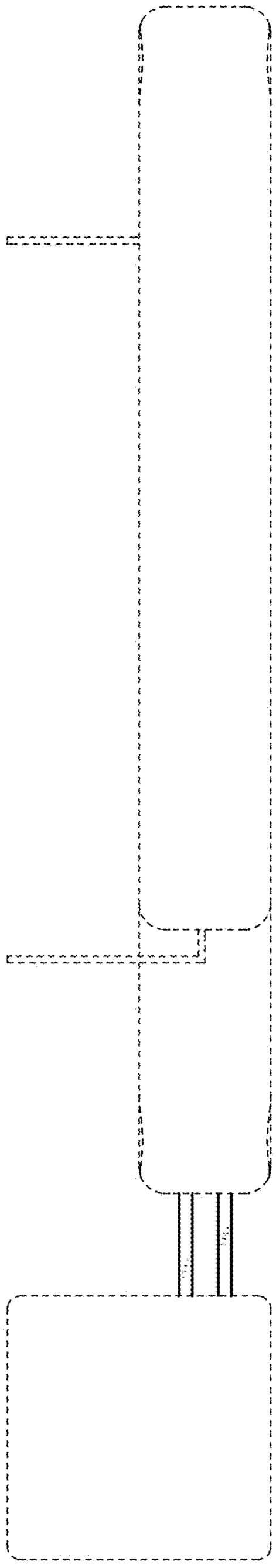

FIG.13

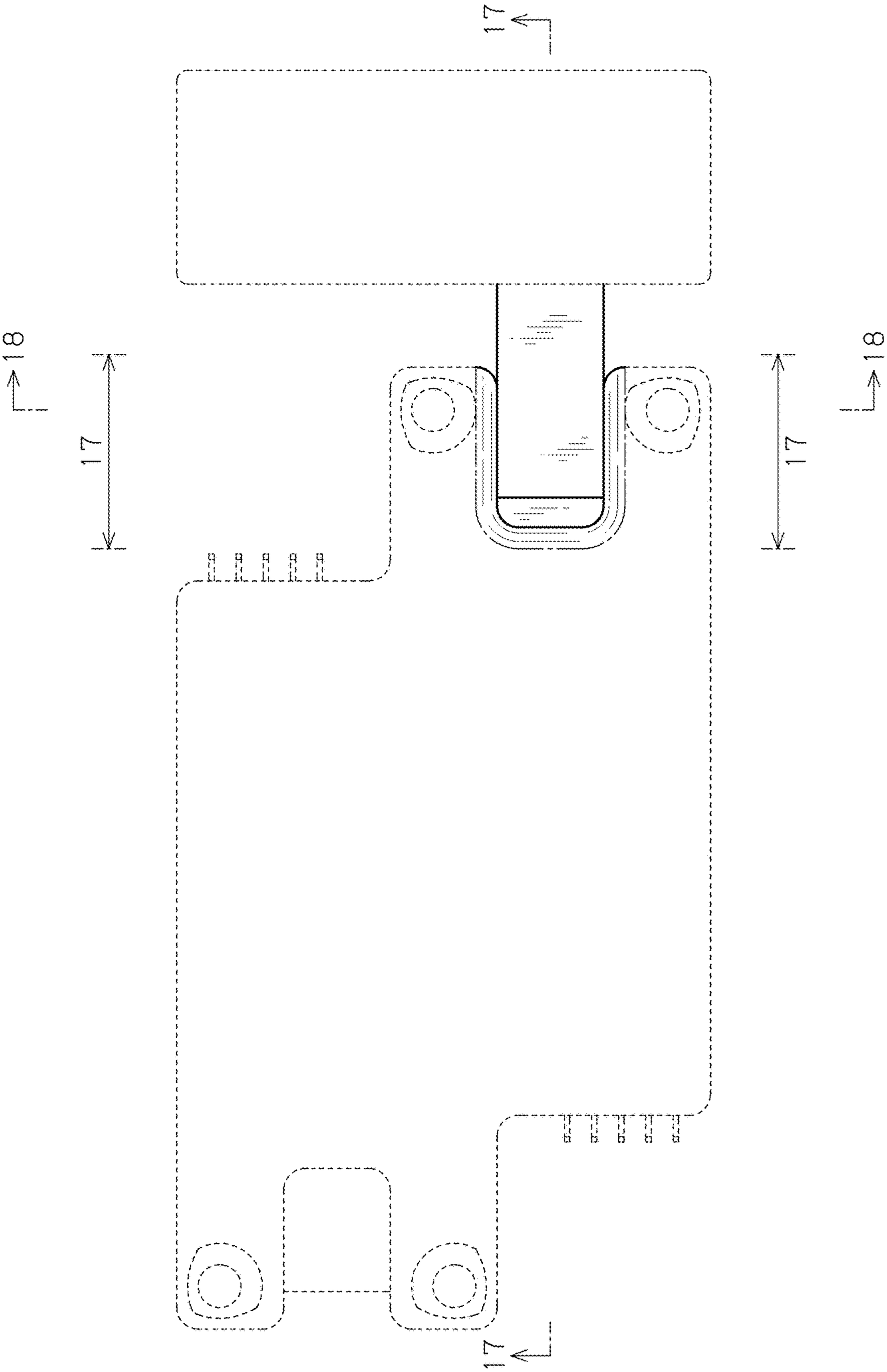

FIG.14

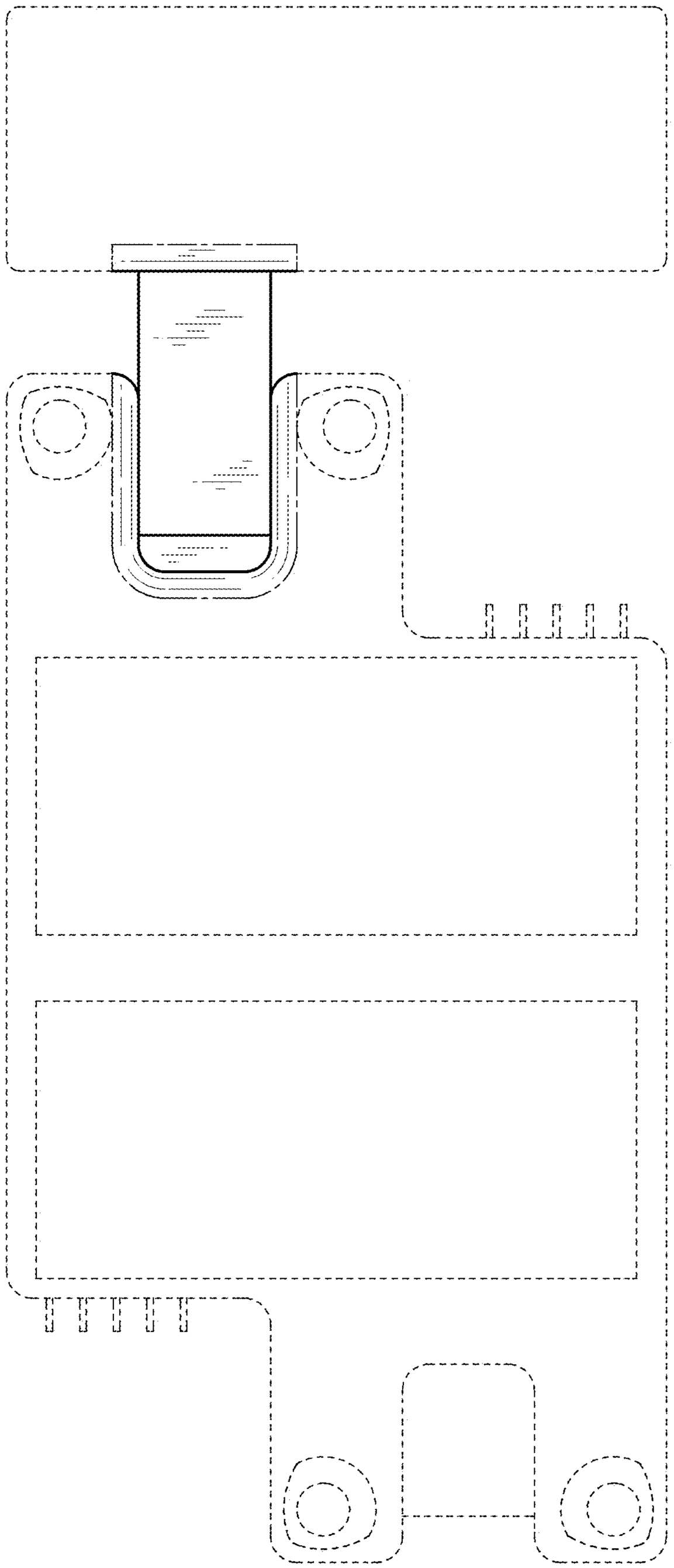

FIG.15

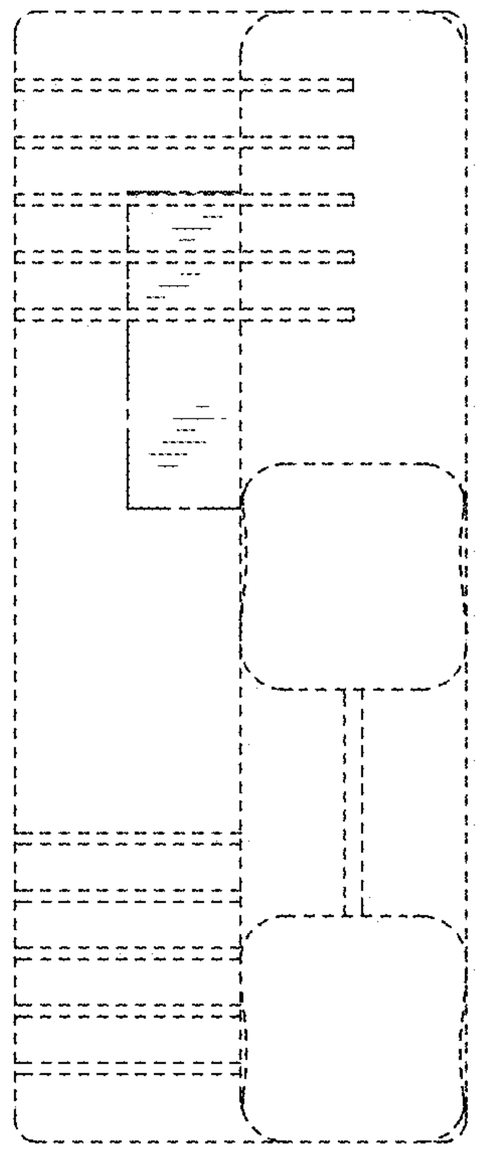

FIG.16

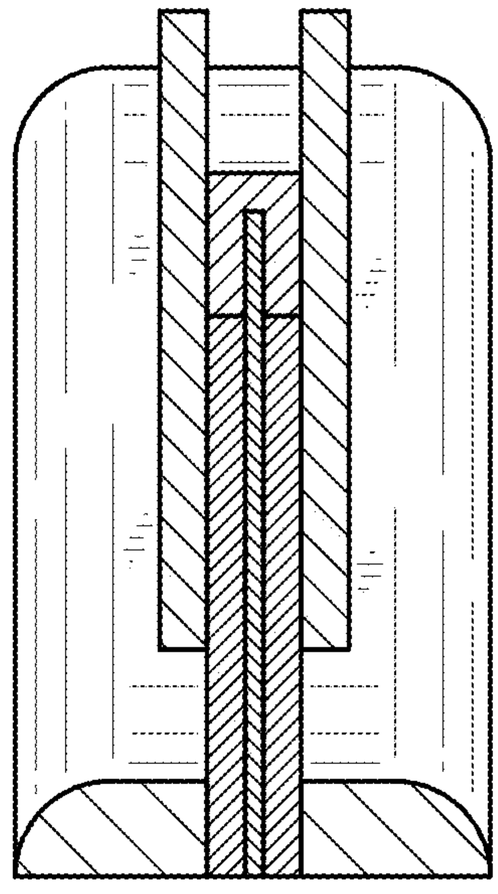

FIG.17

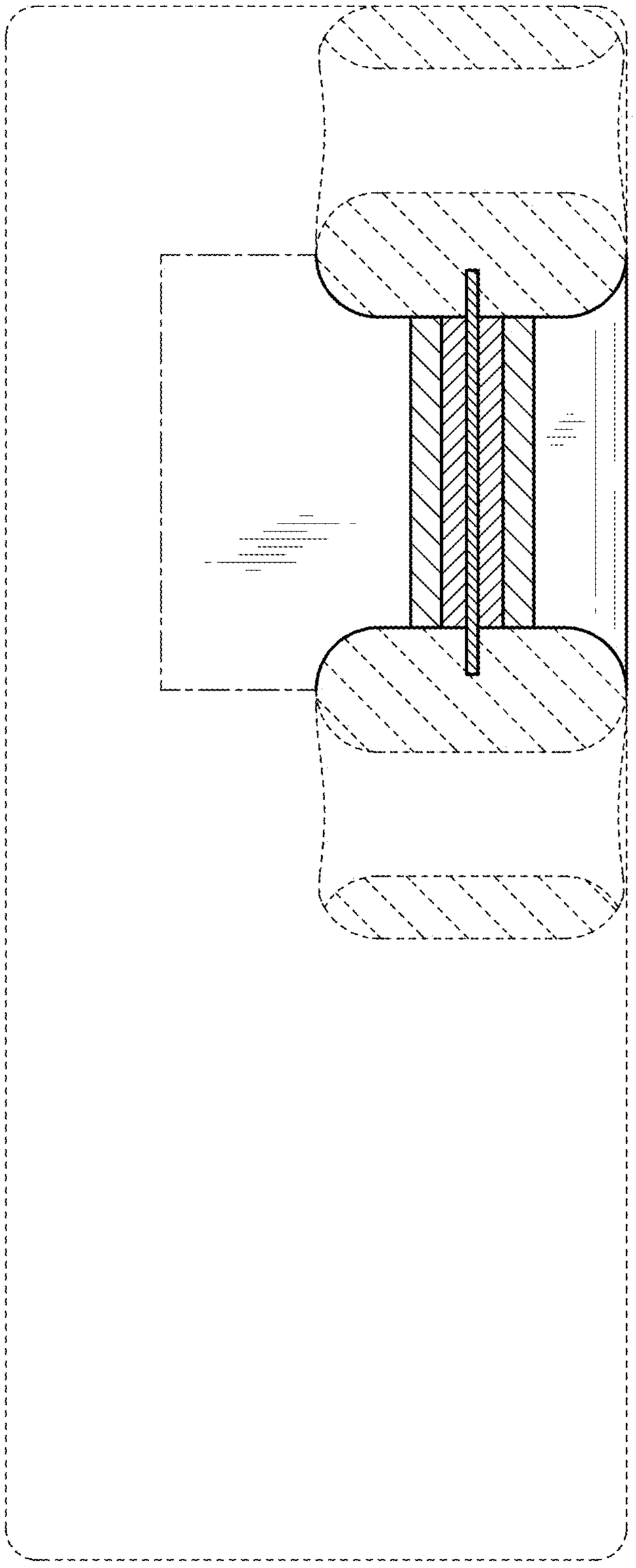

FIG.18